



SOT1438-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 28 terminals; body 3.5 x 7.5 x 0.85

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HVSON
Package type industry code	HVSON28
Package style descriptive code	HTQFN (thermal enhanced thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.4	-	7.5	7.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	28	-	



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2. Package outline

HVSON28: plastic thermal enhanced extremely thin quad flat package; no leads; 28 terminals; body 3.5 x 7.5 x 0.85

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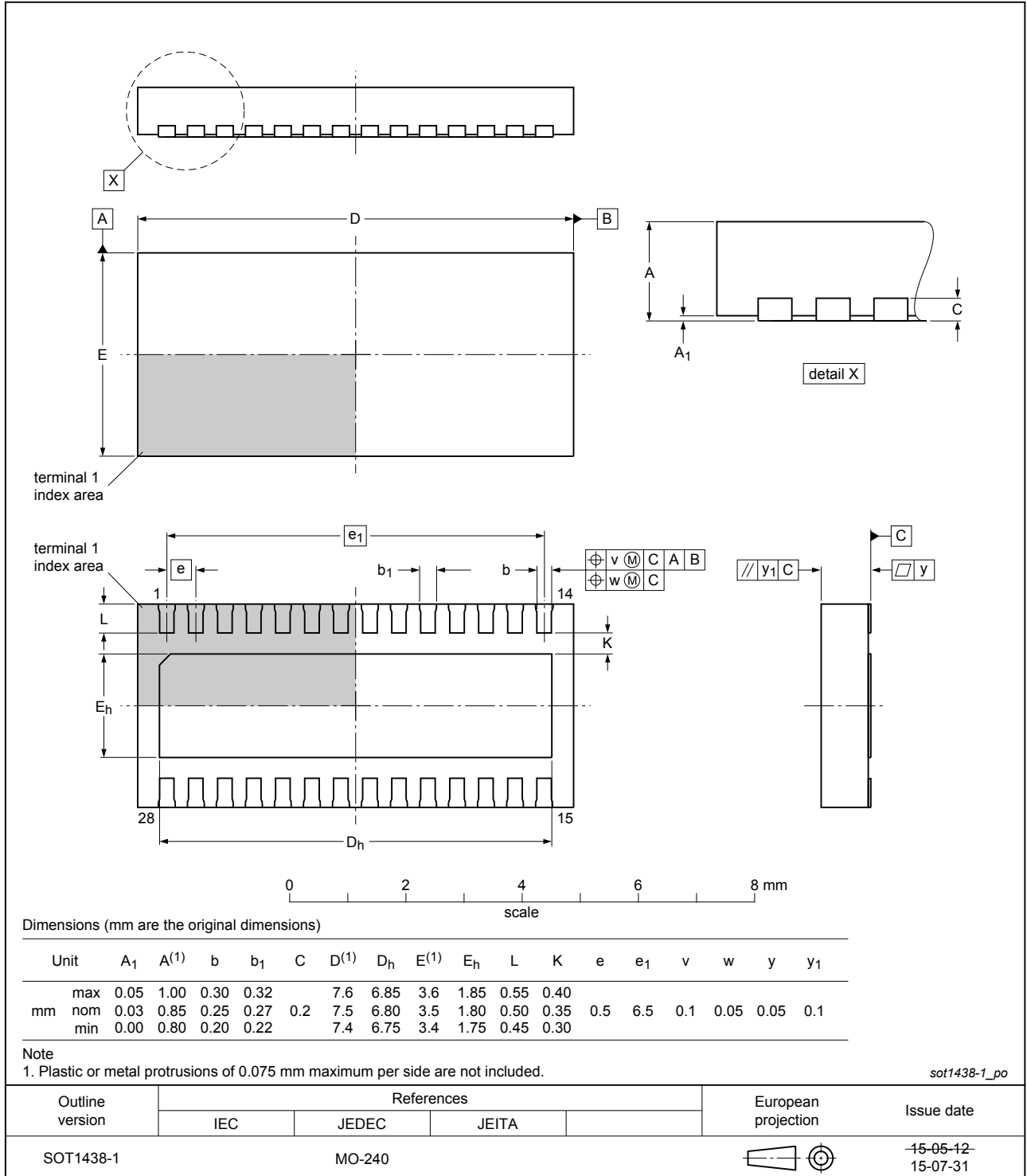


Fig. 1. Package outline HVSON28 (SOT1438-1)

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3. Legal information

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